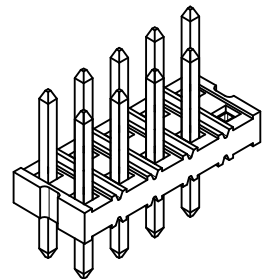
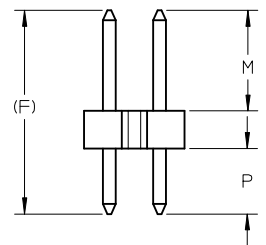
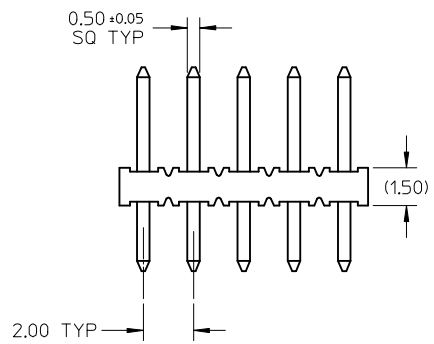


PCB LAYOUT: COMPONENT SIDE



NOTES:

1. MATERIAL:
HSG: NYLON, GLASS-FILLED, UL94V-0 COLOR: BLACK
PIN: 0.50MM SQ, COPPER ALLOY
2. PLATING TYPE:
 - (1) GOLD FLASH OVER
1.25µm MIN. NICKEL OVERALL.
 - (2) GOLD FLASH ON CONTACT AND
2.50µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - (3) 0.38µm MIN. GOLD PLATE ON CONTACT AND
2.00µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - (4) 0.75µm MIN. GOLD PLATE ON CONTACT AND
2.00µm MIN. TIN ON SOLDER TAIL OVER
1.25µm MIN. NICKEL OVERALL.
 - (5) 2.50µm MIN. TIN OVERALL
1.25µm MIN. NICKEL OVERALL
3. PRODUCT SPECIFICATION: PS-87761-100
4. PACKAGING TYPE: SEE TABLE
5. WAFER TO BE FLAT WITHIN 0.003 mm/mm
6. IRREGULAR CIRCUIT CUTOFF WITHIN BREAKAWAY SECTION IS PERMISSIBLE. CUTTING OR CHIPPING OF THE MAIN BODY IS NOT ACCEPTABLE
7. RECOMMENDED PCB THICKNESS IS 1.60mm±0.10
8. THE ABOVE CKT 10 (WITH VOID PIN) IS FOR ILLUSTRATION PURPOSE ONLY
9. PACKAGING SPECIFICATION:
TRAY: PK-89990-487

SEE SHEET 2 EC NO: S2015-1446 DRW/NAT/SEE 2013/12/02 CHK'D: NARAKRI SHIMA 2015/06/12 APPR: KPRASAD 2015/06/26	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$\nabla_{\text{F}} = 0$ $\nabla_{\text{G}} = 0$ $\nabla_{\text{P}} = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY SKLIM01	DATE 2005/10/05	TITLE CUSTOM HEADER 2MM DUAL ROW SINGLE WAFER, VERTICAL T/H HDR		molex SD-87758-108		SHEET NO. 1 OF 2
	ANGULAR ± 3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY BHLOW	DATE 2005/10/18	APPROVED BY PTLIM DATE 2005/10/18				MATERIAL NO. SEE TABLE
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

CKT SIZE	DIMENSION	
	A	B
04	4.00	2.00
06	6.00	4.00
08	8.00	6.00
10	10.00	8.00
12	12.00	10.00
14	14.00	12.00
16	16.00	14.00
18	18.00	16.00
20	20.00	18.00
22	22.00	20.00
24	24.00	22.00
26	26.00	24.00
28	28.00	26.00
30	30.00	28.00
32	32.00	30.00
34	34.00	32.00
36	36.00	34.00
38	38.00	36.00
40	40.00	38.00
42	42.00	40.00
44	44.00	42.00
46	46.00	44.00
48	48.00	46.00
50	50.00	48.00

PART NO. IN BULK	PART NO. IN TRAY	CKT SIZE	PEG	PLATE OPT.	VOID PIN POSITION	DIMENSION		F
						MATING END	SOLDER TAIL	
						M	P	
-	87758-0647	06	N	3	-	6.85	3.10	11.45
-	87758-0808	08	N	4	-	4.00	4.20	9.70
-	87758-1007	10	N	3	10	4.00	2.60	8.10
-	87758-1008	10	N	4	10	4.00	3.20	8.70
-	87758-1012	10	N	3	-	7.65	2.60	11.75
-	87758-0014	14	N	3	-	5.50	1.40	8.40
-	87758-1492	14	N	5	-	10.00	2.90	14.40
-	87758-0016	16	N	5	-	6.30	2.50	10.30
-	87758-0017	16	N	5	-	6.60	2.60	10.70
-	87758-2608	26	N	4	-	4.00	4.20	9.70
-	87758-4000	40	N	3	-	7.90	3.40	12.80
-	87758-4471	44	N	4	19	4.00	2.60	8.10
-	87758-4477	44	N	3	20	4.00	2.60	8.10
-	87758-0050	50	N	3	-	13.00	4.20	18.70

QUALITY SYMBOLS	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC			
$\nabla_A = 0$	4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE			
$\nabla_G = 0$	3 PLACES	± ---	± ---	SKL IM 01	2005/10/05	CUSTOM HEADER			
$\nabla_B = 0$	2 PLACES	± 0.2	± ---	CHECKED BY	DATE	2MM DUAL ROW SINGLE			
	1 PLACE	± ---	± ---	BHLOW	2005/10/18	WAFER, VERTICAL T/H HDR			
	0 PLACE	±	±	APPROVED BY	DATE				
				PTL IM	2005/10/18				
		ANGULAR ± 3 °		MATERIAL NO.	DOCUMENT NO.	SD-87758-108		SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				A3					

ib_frame_A3_P_AM_T Rev. G 2012/01/11

9 8 7 6 5 4 3 2 1